

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shinji TAKASE et al.

Application No.: 10/562,356

Confirmation No.: 6294

Filed: December 27, 2005

Art Unit: 1791

For: METHOD OF RESIN SEALING OF
ELECTRONIC COMPONENT AND MOLD
USED IN THE METHOD

Examiner: E. H. Lee

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Madam:

INTRODUCTORY COMMENTS

In response to the Office Action dated October 9, 2008, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.